



## Integrated Circuit Design in Post-Moore Era

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This Special Issue provides a platform for researchers to report their most recent progress in the field of integrated circuits, including integrated circuit design, technology, packaging and testing, etc. It will bring together, from a global perspective, scientists, researchers, end-users, and industry to exchange ideas, advance knowledge and report key issues of the post-Moore era technology. Topics of interest for this Special Issue include but are not limited to:

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- Random access memory (RAM)
- Digital circuit design
- IC measurement and test
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## Message from the Editor-in-Chief

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